IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for resonant or soft switching applications. Incorporated into the device is a rugged co-packaged free wheeling diode with a low forward voltage.

Features

- Low Saturation Voltage using Trench with Fieldstop Technology
- Low Switching Loss Reduces System Power Dissipation
- Optimized for Low Case Temperature in IH Cooker Application
- Low Gate Charge
- These are Pb-Free Devices

Typical Applications

- Inductive Heating
- Consumer Appliances
- Soft Switching

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V _{CES}	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	l _c	30 15	Α
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	120	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	L F	30 15	Α
Diode pulsed current, T _{pulse} limited by T _{Jmax}	I _{FM}	100	Α
Gate-emitter voltage	V_{GE}	±20	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P_D	156 62.5	W
Operating junction temperature range	T_J	–55 to +150	ç
Storage temperature range	T _{stg}	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

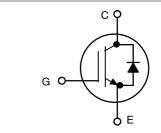
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

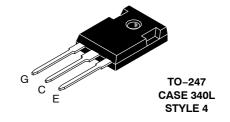


ON Semiconductor®

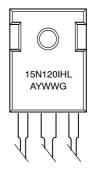
http://onsemi.com

15 A, 1200 V V_{CEsat} = 1.8 V E_{off} = 0.56 mJ





MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB15N120IHLWG	TO-247 (Pb-Free)	30 Units / Rail

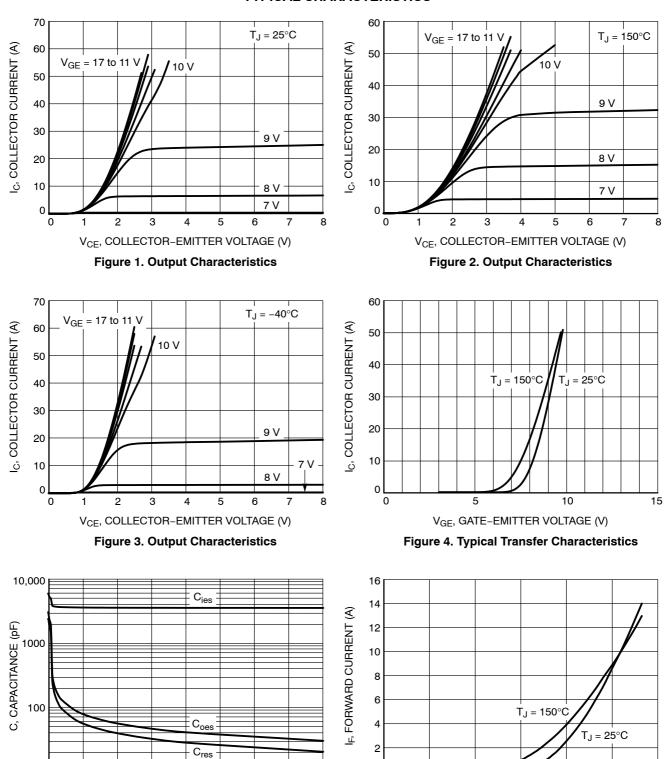
THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ hetaJC}$	0.8	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ hetaJC}$	2.0	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	60	°C/W

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC						
Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0 \text{ V, } I_{C} = 500 \mu\text{A}$	V _{(BR)CES}	1200	_	-	٧
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 15 A V _{GE} = 15 V, I _C = 15 A, T _J = 150°C	V _{CEsat}	- -	1.8 2.0	2.2	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 150 \mu A$	V _{GE(th)}	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V _{GE} = 0 V, V _{CE} = 1200 V V _{GE} = 0 V, V _{CE} = 1200 V, T _{J =} 150°C	I _{CES}	- -	_ _	0.5 2.0	mA
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	-	_	100	nA
DYNAMIC CHARACTERISTIC						
Input capacitance		C _{ies}	-	3600	-	pF
Output capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	88	-	
Reverse transfer capacitance]	C _{res}	-	63	-	
Gate charge total		Q_g		160		nC
Gate to emitter charge	V _{CE} = 600 V, I _C = 15 A, V _{GE} = 15 V	Q _{ge}		30		
Gate to collector charge		Q _{gc}		73		
SWITCHING CHARACTERISTIC, INDUCT	TIVE LOAD					
Turn-off delay time	T _J = 25°C	t _{d(off)}		165		ns
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 15 \text{ A}$ $R_{q} = 15 \Omega$	t _f		200		
Turn-off switching loss	V _{GE} = 0 V/ 15V	E _{off}		0.56		mJ
Turn-off delay time	T _J = 125°C	t _{d(off)}		180		ns
Fall time	V_{CC} = 600 V, I_{C} = 15 A R_{q} = 15 Ω	t _f		260		
Turn-off switching loss	V _{GE} = 0 V/ 15V	E _{off}		0.95		mJ
DIODE CHARACTERISTIC						
Forward voltage	V _{GE} = 0 V, I _F = 15 A V _{GE} = 0 V, I _F = 15 A, T _J = 150°C	V _F		1.4 1.5	1.6	V

TYPICAL CHARACTERISTICS



V_{CE}, COLLECTOR-EMITTER VOLTAGE (V) Figure 5. Typical Capacitance

100

125

75

10

 $\label{eq:VF} V_F, \mbox{ FORWARD VOLTAGE (V)}$ Figure 6. Diode Forward Characteristics

0.75

1.25

1.50

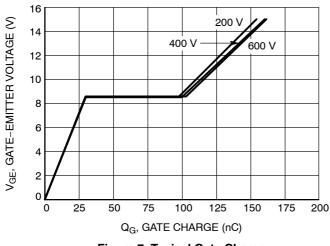
200

0

0.25

0.50

TYPICAL CHARACTERISTICS



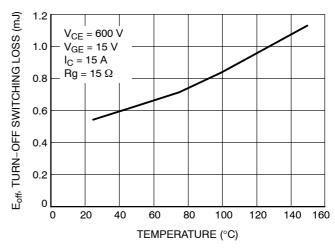
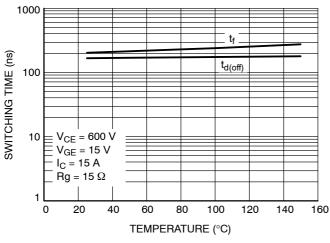


Figure 7. Typical Gate Charge

Figure 8. Energy Loss vs. Temperature



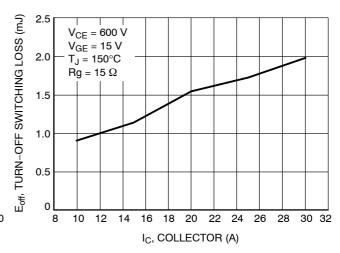
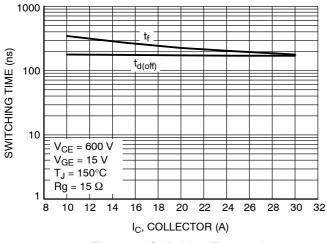


Figure 9. Switching Time vs. Temperature

Figure 10. Energy Loss vs. I_C



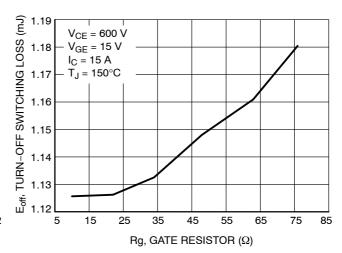


Figure 11. Switching Time vs. I_C

Figure 12. Energy Loss vs. Rg

TYPICAL CHARACTERISTICS

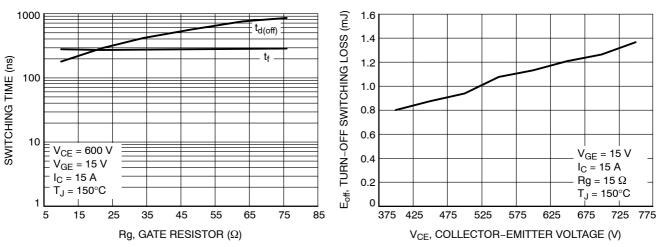


Figure 13. Switching Time vs. Rg



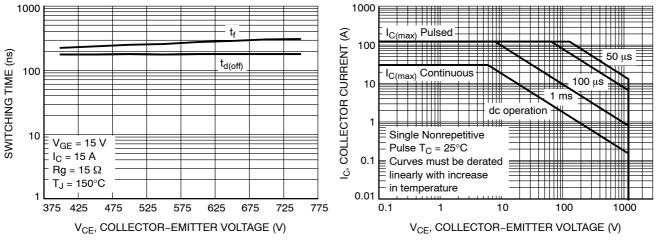


Figure 15. Switching Time vs. V_{CE}

Figure 16. Safe Operating Area

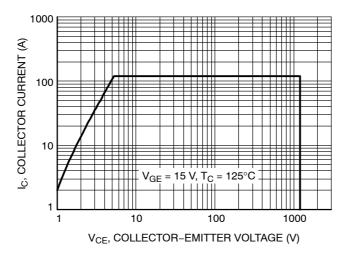


Figure 17. Reverse Bias Safe Operating Area

TYPICAL CHARACTERISTICS

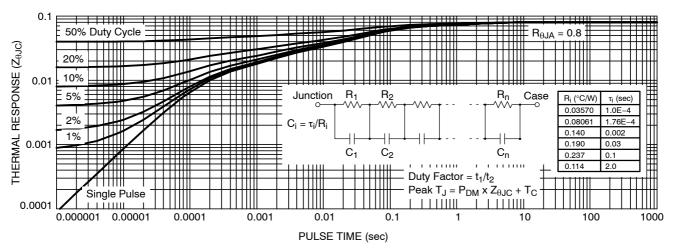


Figure 18. IGBT Transient Thermal Impedance

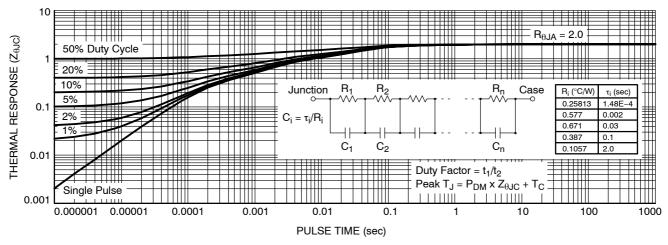


Figure 19. Diode Transient Thermal Impedance

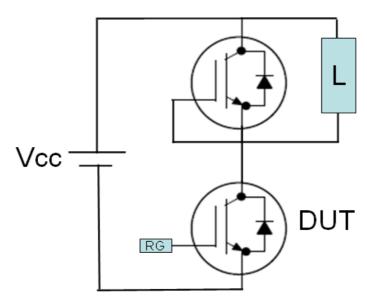


Figure 20. Test Circuit for Switching Characteristics

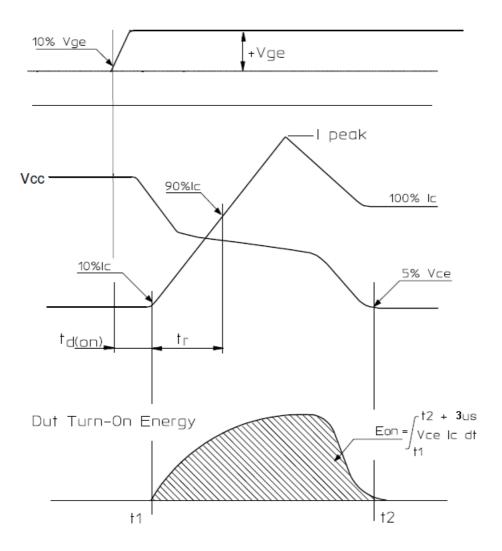


Figure 21. Definition of Turn On Waveform

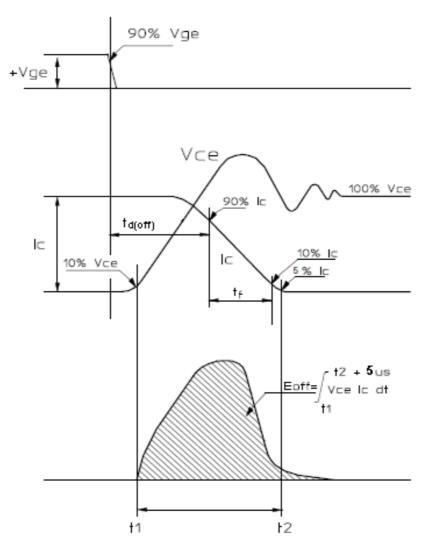
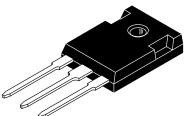


Figure 22. Definition of Turn Off Waveform





TO-247 CASE 340L ISSUE G

DATE 06 OCT 2021

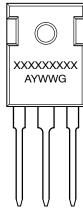
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER

	MILLIMETERS		INC	HES	
DIM	MIN.	MAX.	MIN.	MAX.	
Α	20.32	21.08	0.800	0.830	
В	15.75	16.26	0.620	0.640	
С	4.70	5.30	0.185	0.209	
D	1.00	1.40	0.040	0.055	
Ε	1.90	2.60	0.075	0.102	
F	1.65	2.13	0.065	0.084	
G	5.45 BSC		0.215	0.215 BSC	
I	1.50	2.49	0.059	0.098	
J	0.40	0.80	0.016	0.031	
K	19.81	20.83	0.780	0.820	
١	5.40	6.20	0.212	0.244	
N	4.32	5.49	0.170	0.216	
Ρ		4.50		0.177	
Q	3.55	3.65	0.140	0.144	
٦	6.15	BSC	0.242	BSC	
W	2.87	3.12	0.113	0.123	

NOTES:

SCALE 1:1 Α øΩ 2X F 3X D

GENERIC MARKING DIAGRAM*



STYLE 1: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

PIN 1. CATHODE 2. ANODE

3. GATE 4. ANODE

STYLE 5:

STYLE 2: PIN 1. ANODE 2. CATHODE (S) 3. ANODE 2 4. CATHODES (S)

PIN 1. MAIN TERMINAL 1 2. MAIN TERMINAL 2

3. GATE 4. MAIN TERMINAL 2

STYLE 6:

♦0.25 (0.010)**₩** Y AS

STYLE 3: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR STYLE 4: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

XXXXX = Specific Device Code = Assembly Location Α

Υ = Year WW = Work Week = Pb-Free Package G

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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